

## Prevalence of Workplace Bullying in Hong Kong: A Latent Class Analysis

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**Abstract :** Workplace bullying is generally defined as a form of direct and indirect maltreatment at work including harassing, offending, socially isolating someone or negatively affecting someone's work tasks. Workplace bullying is unfortunately commonplace around the world, which makes it a social phenomenon worth researching. However, the measurements and estimation methods of workplace bullying seem to be diverse in different studies, leading to dubious results. Hence, this paper attempts to examine the prevalence of workplace bullying in Hong Kong using the latent class analysis approach. It is often argued that the traditional classification of workplace bullying into the dichotomous 'victims' and 'non-victims' may not be able to fully represent the complex phenomenon of bullying. By treating workplace bullying as one latent variable and examining the potential categorical distribution within the latent variable, a more thorough understanding of workplace bullying in real-life situations may hence be provided. As a result, this study adopts a latent class analysis method, which was tested to demonstrate higher construct and higher predictive validity previously. In the present study, a representative sample of 2814 employees (Male: 54.7%, Female: 45.3%) in Hong Kong was recruited. The participants were asked to fill in a self-reported questionnaire which included measurements such as Chinese Workplace Bullying Scale (CWBS) and Chinese Version of Depression Anxiety Stress Scale (DASS). It is estimated that four latent classes will emerge: 'non-victims', 'seldom bullied', 'sometimes bullied', and 'victims'. The results of each latent class and implications of the study will also be discussed in this working paper.

**Keywords :** latent class analysis, prevalence, survey, workplace bullying

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